REMARKS

This paper is filed in response to the Office Action mailed on March 29, 2007. Presently, Claims 1-24 are pending in the application. Claims 1-24 has been examined and stand rejected.

Applicants submit that Claims 1, and 3-24 are pending, Claim 2 having been previously canceled.

Reconsideration of Claims 1 and 3-24 is respectfully requested.

The Rejection of Claims 1 and 3-24 Under 35 U.S.C. § 103(a)

Claims 1 and 3-24 are rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 4,943,516 (Kamayachi et al.) in view of U.S. Patent No. 5,626,774 (Paulus) and further in view of applicants' purportedly admitted prior art (AAPA).

Claims 1, 4, 7, and 22 have been amended to recite that, "following laminating, a laser beam is irradiated onto the laminated semi-cured thermosetting film." Claims 3, 6, 9, and 15 recite "following curing, irradiating a laser beam to the laminated cured thermosetting film." Claims 16-21 have been canceled without prejudice of disclaimer.

In one embodiment, according to Kamayachi et al., a dry film, not a semi-cured film, is laminated, followed by exposure to a laser beam. (Col. 16, lines 5-6.) Alternatively in another embodiment, Kamayachi et al. teaches that if the composition is applied in the form of a liquid, a dry film is laminated on the applied layer of the liquid composition in a wet state or a dry state. (Col. 16, lines 6-9.)

Accordingly, Kamayachi et al. does not teach or suggest laminating a semi-cured thermosetting film, and irradiating a laser beam onto the laminated semi-cured thermosetting film. Kamayachi et al. also does not teach laminating a semi-cured thermosetting film, followed by curing the thermosetting film, then followed by irradiating a laser beam onto the laminated

LAW OFFICES OF
CHRISTENSEN O'CONNOR JOHNSON KINDNESS PLLC
1420 Fifth Avenue
Suite 2800
Seattle, Washington 98101
206.682.8100

cured thermosetting film. Accordingly, Kamayachi et al. does not follow the sequence of steps that are recited in the claims.

When Kamayachi et al. applies a liquid composition on the board, Kamayachi et al. follows this by laminating a dry film on the applied layer of the liquid composition in a wet state or a dry state.

Furthermore, the teaching of Paulus, even when combined with Kamayachi et al., does not render the claims obvious.

Paulus teaches that a sheet of copper foil having a partially cured (B-staged) thermosetting resin is applied to circuitry on the surface of the printed circuit board. The resin layer fills the spaces between the circuit features and leaves a layer of resin above the circuit features which will serve as a solder mask. However, following application of the copper foil and B-stage resin, Paulus does not teach irradiating with a laser beam; rather, Paulus teaches applying an etch resist to the surface of the copper foil and photo imaging. Following this, the uncured portions of the etch resist are removed with a solvent to expose copper areas. Following this, the exposed copper is etched away, leaving the resin layer exposed. Only then is the resin removed by ablation techniques, such as plasma or laser, to expose the copper circuit feature to which a solder connection will be made.

Accordingly, Paulus does not teach the exact sequence of steps as claimed.

Therefore, because a *prima facie* rejection requires that all the claim limitations be taught or suggested in the prior art references, the withdrawal of the rejection is respectfully requested.

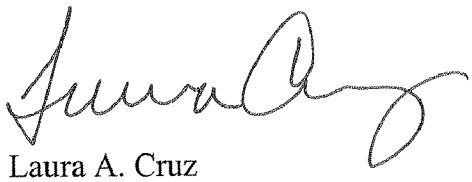
LAW OFFICES OF
CHRISTENSEN O'CONNOR JOHNSON KINDNESS[PLLC]
1420 Fifth Avenue
Suite 2800
Seattle, Washington 98101
206.682.8100

CONCLUSION

In view of the foregoing amendments and remarks, applicants submit that Claims 1, 3-15, and 22-24 are allowable. If the Examiner has any further questions or comments, the Examiner may contact the applicants' attorney at the number provided below.

Respectfully submitted,

CHRISTENSEN O'CONNOR
JOHNSON KINDNESS[PLLC]



Laura A. Cruz
Registration No. 46,649
Direct Dial No. 206.695.1725

LXC:pww/mmw

LAW OFFICES OF
CHRISTENSEN O'CONNOR JOHNSON KINDNESS[PLLC]
1420 Fifth Avenue
Suite 2800
Seattle, Washington 98101
206.682.8100